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Dimensions

Chip Size	1206
L	3.2mm +0.94/-0.25mm (0.126 in +0.037/-0.01 in)
W	1.6mm +0.68/-0.25mm (0.063 in +0.027/-0.01 in)
T	1.8mm MAX (0.071 in MAX)
B	0.51mm +/-0.36mm (0.02 in +/-0.014 in)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	126

General Information

Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov
Termination	Solder Dipped
Failure Rate	N/A
Qualifications	MIL-PRF-32535 M-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	560 pF
Capacitance Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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